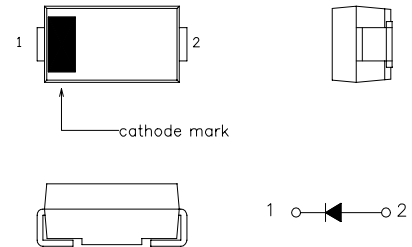


FRD Type : EC11FS2

FEATURES

- * Miniature Size, Surface Mount Device
- * Ultra-Fast Recovery
- * Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight:0.06g

| Rating | Symbol | EC11FS2 | | Unit |
|--------------------------------------|--------------|-------------|--|------------------------------------|
| Repetitive Peak Reverse Voltage | V_{RRM} | 200 | | V |
| Non-repetitive Peak Reverse Voltage | V_{RSM} | 220 | | V |
| Average Rectified Output Current | I_O | 0.81 | $T_a=25^{\circ}C$ *1 | 50Hz Half Sine Wave Resistive Load |
| | | 1.0 | $T_a=34^{\circ}C$ *2 | |
| RMS Forward Current | $I_{F(RMS)}$ | 1.57 | | A |
| Surge Forward Current | I_{FSM} | 20 | 50Hz Half Sine Wave, 1cycle Non-repetitive | A |
| Operating Junction Temperature Range | T_{jw} | -40 to +150 | | $^{\circ}C$ |
| Storage Temperature Range | T_{stg} | -40 to +150 | | $^{\circ}C$ |

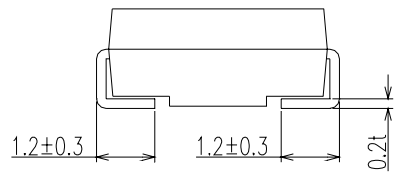
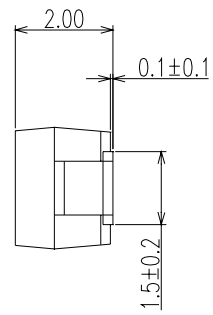
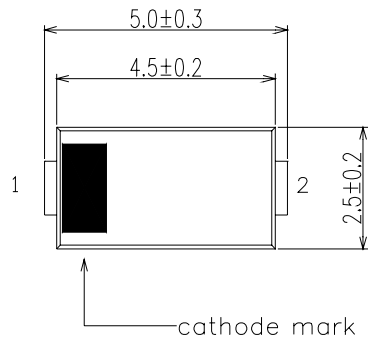
Electrical • Thermal Characteristics

| Characteristics | Symbol | Conditions | Min. | Typ. | Max. | Unit | |
|-----------------------|---------------|---|------|------|------|---------|---------------|
| Peak Reverse Current | I_{RM} | $T_j= 25^{\circ}C, V_{RM}= V_{RRM}$ | - | - | 10 | μA | |
| Peak Forward Voltage | V_{FM} | $T_j= 25^{\circ}C, I_{FM}= 1.0A$ | - | - | 0.98 | V | |
| Reverse Recovery Time | trr | $I_{FM}= 1A, -di/dt= 50A/\mu s, T_a= 25^{\circ}C$ | - | - | 30 | ns | |
| Thermal Resistance | $R_{th(j-a)}$ | Junction to Ambient | *1 | - | - | 157 | $^{\circ}C/W$ |
| | | | *2 | - | - | 108 | |

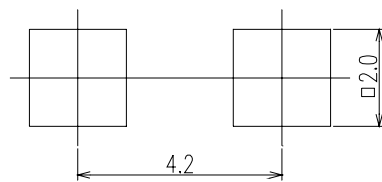
*1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

*2 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

EC11FS2 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD



www.s-manuals.com